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#### (54) WIRING BOARD

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#### (57)ABSTRACT

A wiring board includes a first interconnect structure including a first interconnect layer, and a first insulating layer including a non-photosensitive thermosetting resin as a main component thereof, a second interconnect structure including second interconnect layers, and second insulating layers including a photosensitive resin as a main component thereof, and laminated on the first interconnect structure, and an encapsulating resin layer including a non-photosensitive thermosetting resin as a main component thereof, and laminated on an uppermost second insulating layer. An uppermost second interconnect layer includes a pad protruding from the uppermost second insulating layer. The encapsulating resin layer exposes a top surface of the pad, and covers at least a portion of a side surface of the pad. Thermal expansion coefficients of the first insulating layer and the encapsulating resin layer are lower than that of the second insulating layers.

